

EE461g: Introduction to Electronic Circuits

Lecture 9: NMOS MOSFET

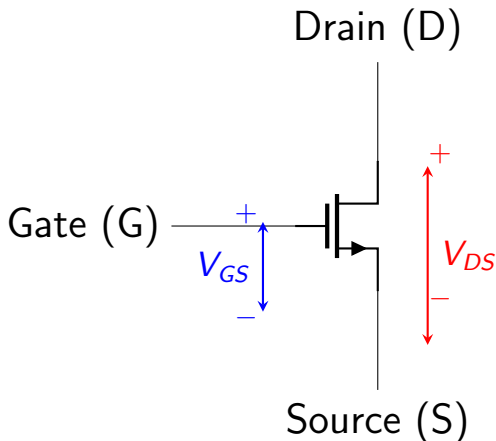
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Outline

- 1 MOSFET Physics (Sec. 6.1–6.2)
- 2 MOSFET Output Characteristics (Sec. 6.3)
- 3 Common Source Amplifier (Sec. 7.2)
- 4 Operating Regions and Load Line (Sec. 6.2.2, 7.2)
- 5 Concept of Transconductance (Sec. 7.2.3)
- 6 Small-Signal Model (Sec. 7.2.4)

(Sec. 6.1) NMOS MOSFET Symbol



- **Gate (G):** Controls the channel (high impedance input)
- **Drain (D):** Current flows out of drain
- **Source (S):** Current flows into source (reference for V_{GS})

neamen_06.png

Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

neamen_01.png

Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

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Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

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Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

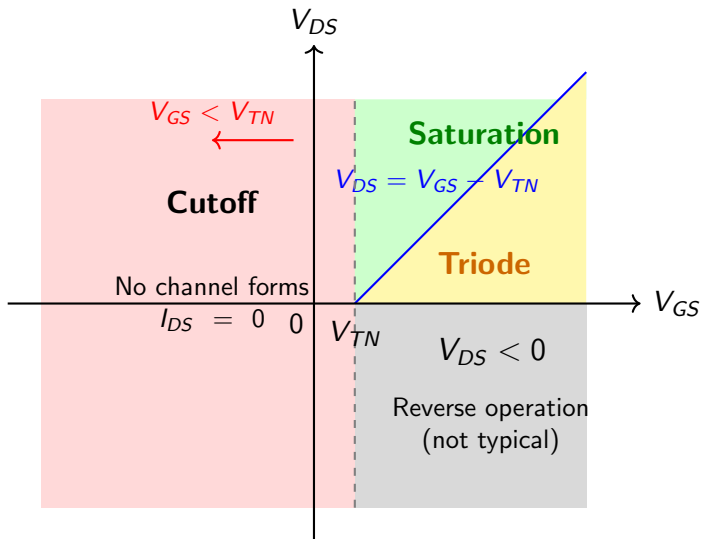
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Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

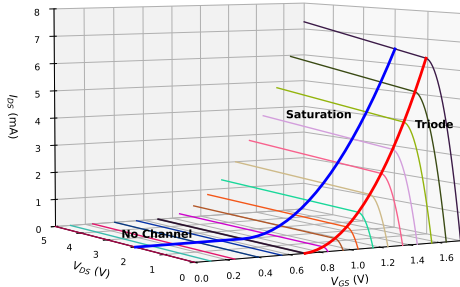
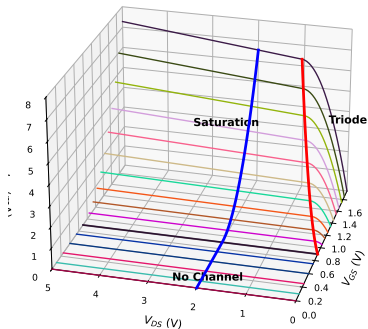
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Source: Neamen, *Microelectronics: Circuit Analysis and Design*, 4th ed.

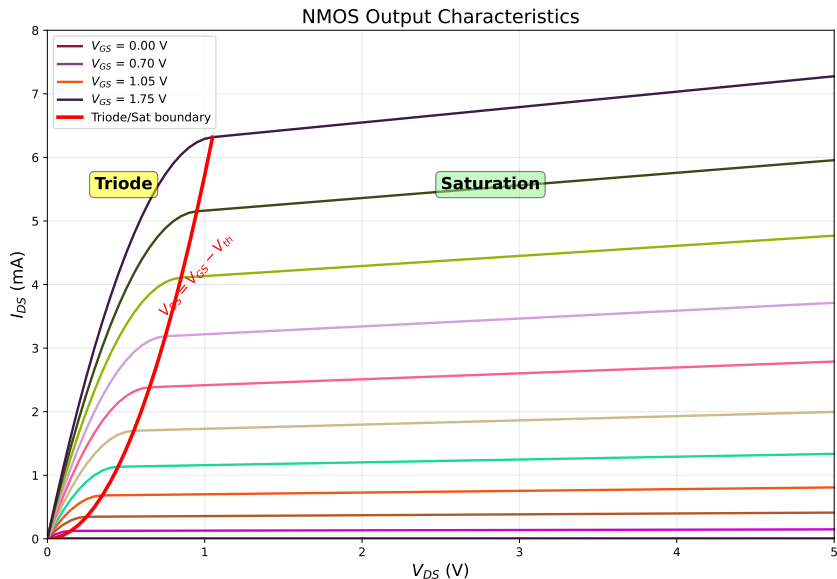
(Sec. 6.2) MOSFET Operating Space: V_{GS} vs V_{DS}



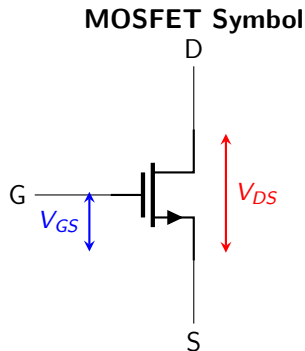
(Sec. 6.2.2) NMOS Output Characteristics – 3D View



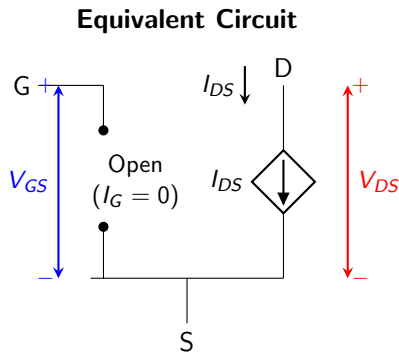
(Sec. 6.2.2) NMOS Output Characteristics – 2D View



(Sec. 6.3.1) NMOS Large-Signal Model (Square Law)



Model $\rightarrow$



$$I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2 \quad (\text{saturation})$$

(Sec. 6.2.2) NMOS Operating Regions

Region	Condition	Current
Cutoff	$V_{GS} < V_{TN}$	$I_{DS} = 0$
Triode	$V_{GS} \geq V_{TN}$ $V_{DS} < V_{GS} - V_{TN}$	$I_{DS} = \frac{K_n}{2} [2(V_{GS} - V_{TN})V_{DS} - V_{DS}^2]$
Saturation	$V_{GS} \geq V_{TN}$ $V_{DS} \geq V_{GS} - V_{TN}$	$I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2$

$$K_n = \mu_n C_{ox} \frac{W}{L} \quad (\text{process \& geometry dependent})$$

- The quantity $(V_{GS} - V_{TN})$ is called the **overdrive voltage**
- Saturation boundary: $V_{DS} = V_{GS} - V_{TN}$

(Sec. 6.2.2) Deriving the Saturation Equation from Triode

Triode Region Equation:

$$I_{DS} = \frac{K_n}{2} [2(V_{GS} - V_{TN})V_{DS} - V_{DS}^2]$$

At the saturation boundary: $V_{DS} = V_{GS} - V_{TN}$

Substitute $V_{DS} = V_{GS} - V_{TN}$ into the triode equation:

$$\begin{aligned} I_{DS} &= \frac{K_n}{2} [2(V_{GS} - V_{TN}) \cdot (V_{GS} - V_{TN}) - (V_{GS} - V_{TN})^2] \\ &= \frac{K_n}{2} [2(V_{GS} - V_{TN})^2 - (V_{GS} - V_{TN})^2] \\ &= \frac{K_n}{2} (V_{GS} - V_{TN})^2 \end{aligned}$$

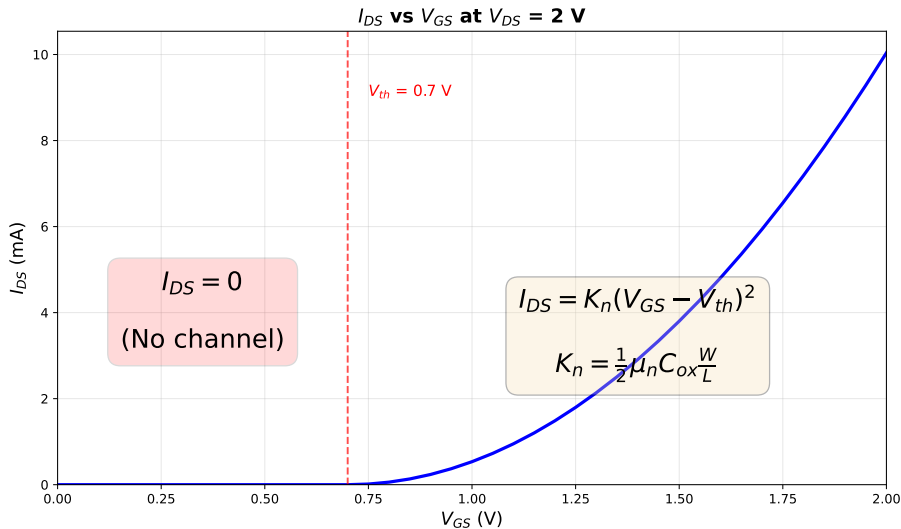
Saturation Region Equation:

$$I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2$$

(Sec. 6.2.2) Triode as a Parabola, Saturation as the Peak

triode_parabola.pdf

(Sec. 6.2.2) I_{DS} vs V_{GS} (Transfer Characteristic)

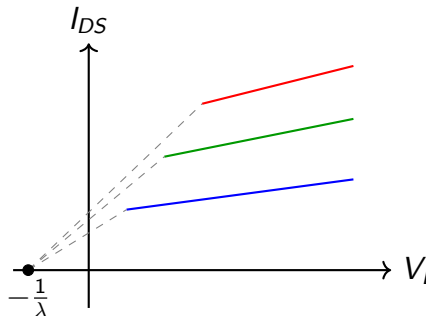


(Sec. 6.2.3) Channel-Length Modulation

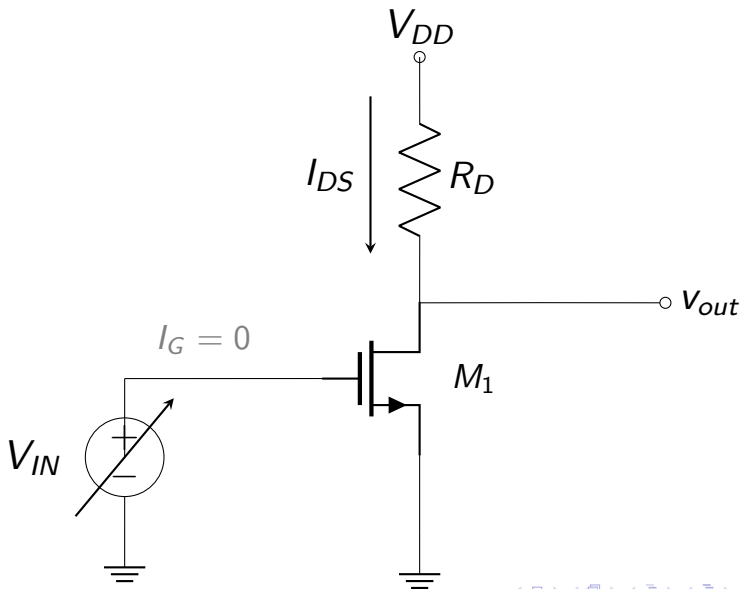
In saturation, I_{DS} is **not perfectly constant** — it increases slightly with V_{DS} :

$$I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2 (1 + \lambda V_{DS})$$

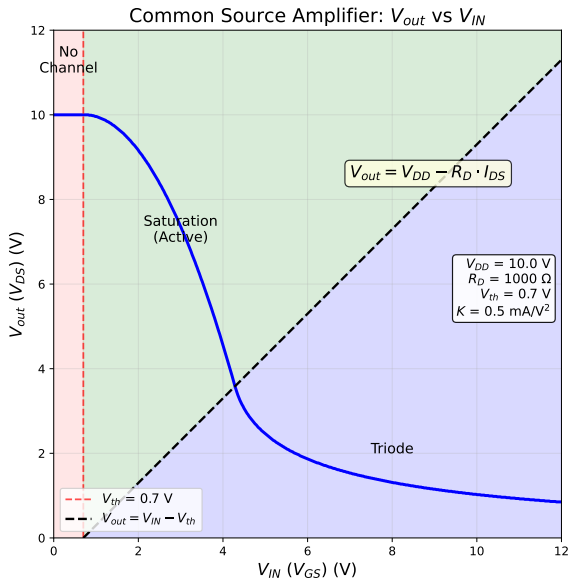
- λ = channel length modulation parameter ($1/V$)
- Similar to Early effect in BJT
- Causes finite output resistance:
 $r_o = \frac{1}{\lambda I_{DS}}$
- Extrapolating I_{DS} curves backward, they meet at $V_{DS} = -1/\lambda$



(Sec. 7.2) Common Source Amplifier



(Sec. 7.2) Common Source Amplifier – V_{out} vs V_{IN}



(Sec. 7.2) Deriving V_{out} vs V_{IN} by Hand

- **Starting point** (KVL through R_D , always true):

$$V_{out} = V_{DD} - R_D \cdot I_{DS}$$

- Since the source is grounded: $V_{GS} = V_{IN}$ and $V_{DS} = V_{out}$
- Choose I_{DS} based on the operating region:

Region	Condition	I_{DS}
No Channel	$V_{IN} < V_{TN}$	$I_{DS} = 0$
Saturation	$V_{out} \geq V_{IN} - V_{TN}$	$I_{DS} = \frac{K_n}{2} (V_{IN} - V_{TN})^2$
Triode	$V_{out} < V_{IN} - V_{TN}$	$I_{DS} = \frac{K_n}{2} [2(V_{IN} - V_{TN})V_{out} - V_{out}^2]$

⇒ **Pick the correct I_{DS} , then substitute into the load line.**

(Sec. 7.2) Substituting into the Load Line

Plug each I_{DS} into $V_{out} = V_{DD} - R_D \cdot I_{DS}$:

- **No Channel** ($V_{IN} < V_{TN}$):

$$V_{out} = V_{DD} \quad (\text{flat plateau})$$

- **Saturation** ($V_{out} \geq V_{IN} - V_{TN}$):

$$V_{out} = V_{DD} - R_D \cdot \frac{K_n}{2} (V_{IN} - V_{TN})^2$$

Explicit function of V_{IN} (downward parabola)

- **Triode** ($V_{out} < V_{IN} - V_{TN}$):

$$V_{out} = V_{DD} - R_D K_n [2(V_{IN} - V_{TN})V_{out} - V_{out}^2]$$

Implicit in V_{out} — must solve numerically or iterate

Key takeaway: Saturation gives a clean, explicit $V_{out}(V_{IN})$ — this is why saturation is the useful amplification region.

(Sec. 6.2.2) Cutoff Region

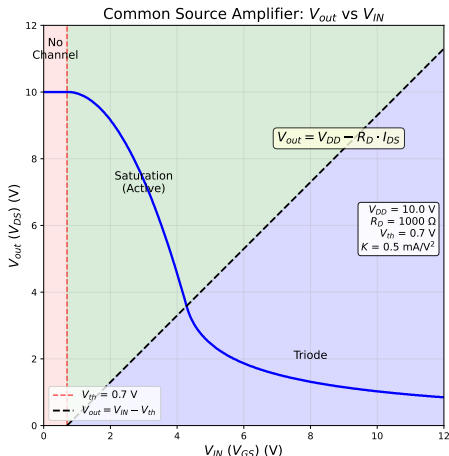
- $V_{IN} < V_{TN}$ (e.g., < 0.7 V)
- No channel forms
- $I_{DS} = 0$

Substitute into the load line:

$$\begin{aligned}V_{out} &= V_{DD} - R_D \cdot I_{DS} \\ &= V_{DD} - R_D \cdot 0\end{aligned}$$

$$V_{out} = V_{DD}$$

Output stays flat at V_{DD}
(transistor is OFF)



(Sec. 6.2.2) Saturation Region (Active)

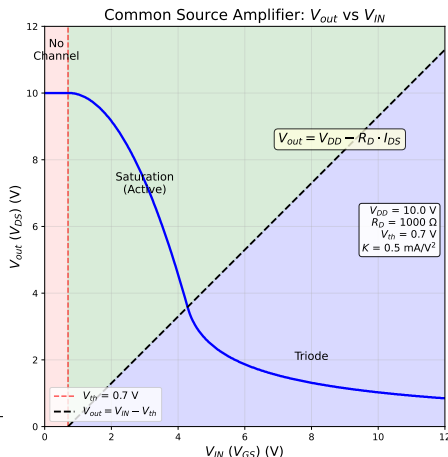
- $V_{IN} > V_{TN}$ and $V_{out} \geq V_{IN} - V_{TN}$
- Channel is pinched off at drain
- $I_{DS} = \frac{K_n}{2}(V_{IN} - V_{TN})^2$

Substitute into the load line:

$$\begin{aligned} V_{out} &= V_{DD} - R_D \cdot I_{DS} \\ &= V_{DD} - R_D \cdot \frac{K_n}{2}(V_{IN} - V_{TN})^2 \end{aligned}$$

$$V_{out} = V_{DD} - R_D \cdot \frac{K_n}{2}(V_{IN} - V_{TN})^2$$

Explicit function of V_{IN} (downward parabola)

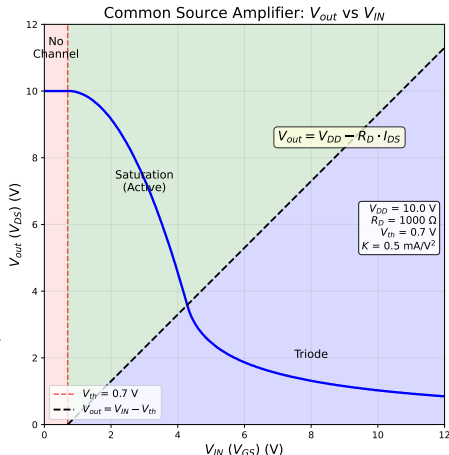


(Sec. 6.2.2) Triode (Linear) Region

- $V_{IN} > V_{TN}$ and $V_{out} < V_{IN} - V_{TN}$
- $I_{DS} = \frac{K_n}{2} [2(V_{IN} - V_{TN})V_{out} - V_{out}^2]$

Substitute into the load line:

$$\begin{aligned} V_{out} &= V_{DD} - R_D \cdot I_{DS} \\ &= V_{DD} - R_D \cdot \frac{K_n}{2} [2(V_{IN} - V_{TN})V_{out} - V_{out}^2] \end{aligned}$$

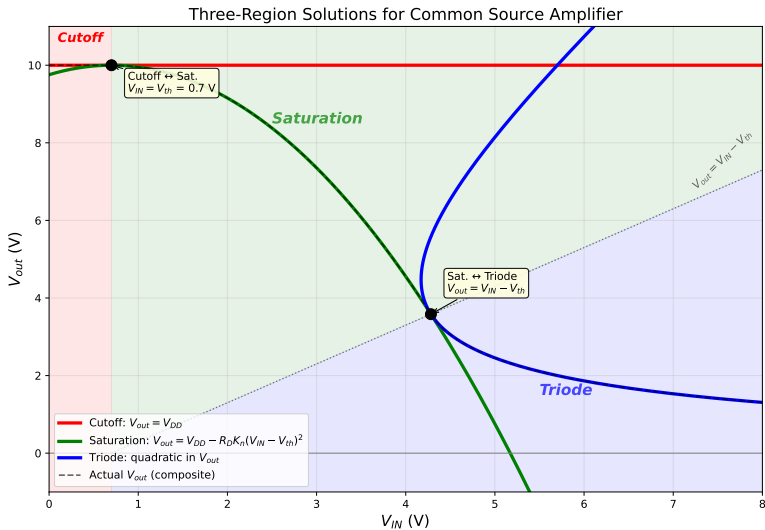


Quadratic in V_{out} (solvable)

Output levels off (MOSFET is fully

ON)

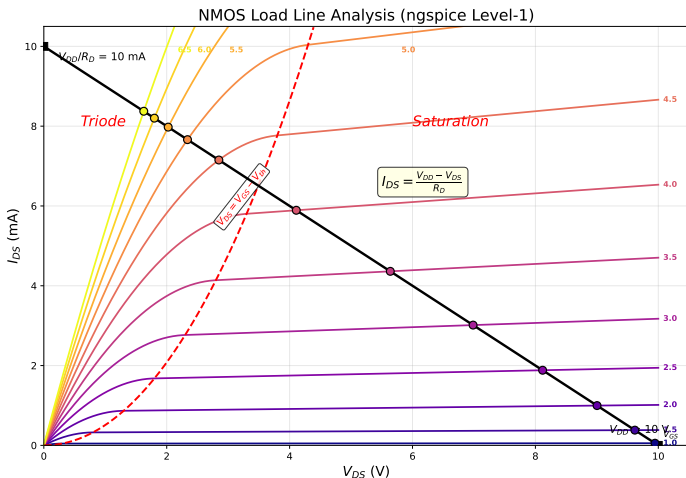
Three-Region Solutions for V_{out} vs V_{IN}



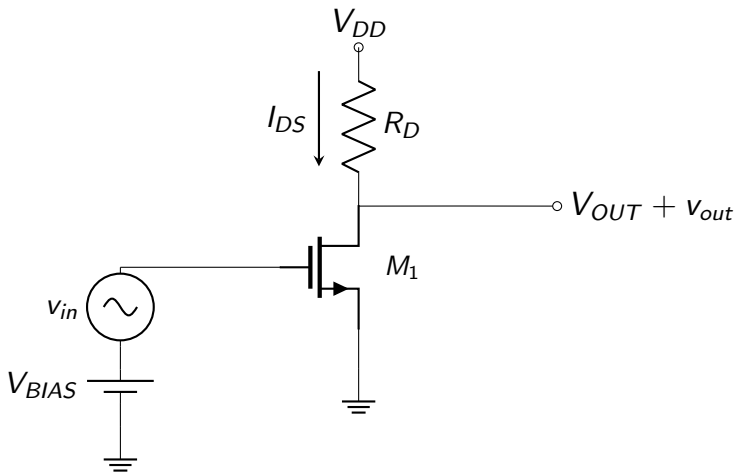
(Sec. 7.2) Load Line Analysis

Load line equation:

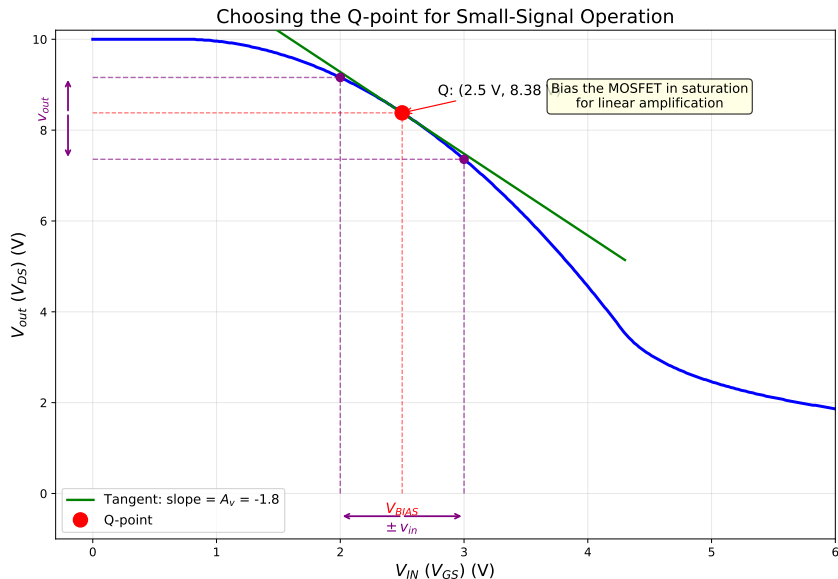
$$I_{DS} = \frac{V_{DD} - V_{DS}}{R_D}$$



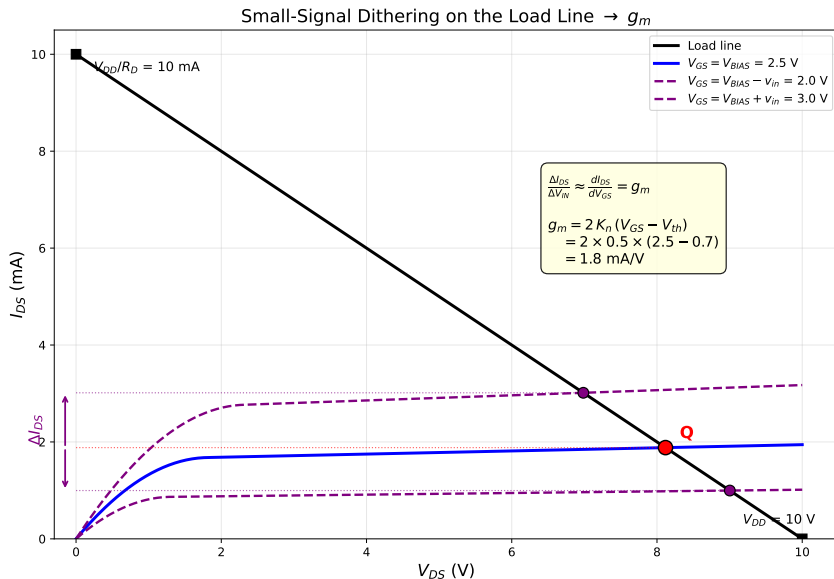
(Sec. 7.2) Common Source Amplifier with Small-Signal Input



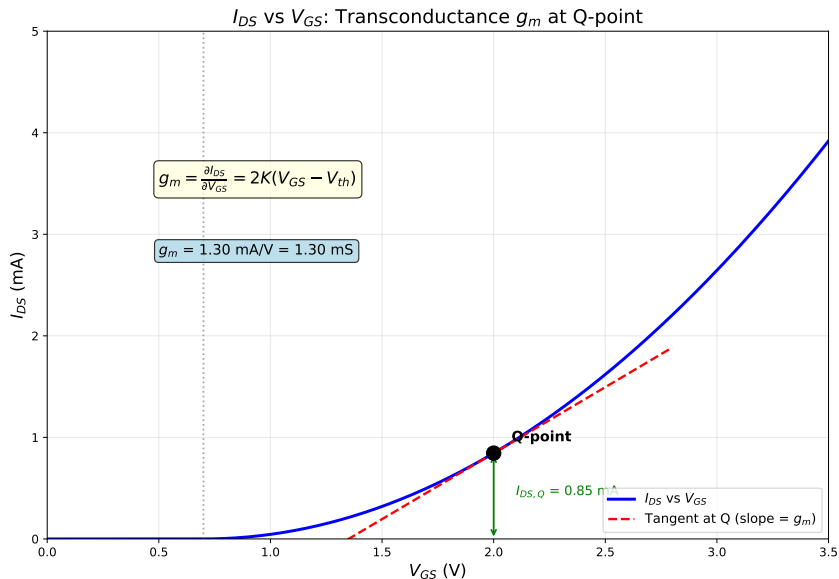
(Sec. 7.2) V_{out} vs V_{IN} — Choosing a Q-point



(Sec. 7.2.3) From Load Line Dithering to g_m



(Sec. 7.2.3) I_{DS} vs V_{GS} : Linearization at the Q-point



(Sec. 7.2.3) Transconductance g_m for MOSFET

Linearizing I_{DS} vs V_{GS} at the Q-point:

$$g_m = \left. \frac{\partial I_{DS}}{\partial V_{GS}} \right|_Q = K_n (V_{GS} - V_{TN}) = \frac{2I_{DS}}{V_{GS} - V_{TN}}$$

g_m tells us: *how much does I_{DS} change for a small change in V_{GS} ?*

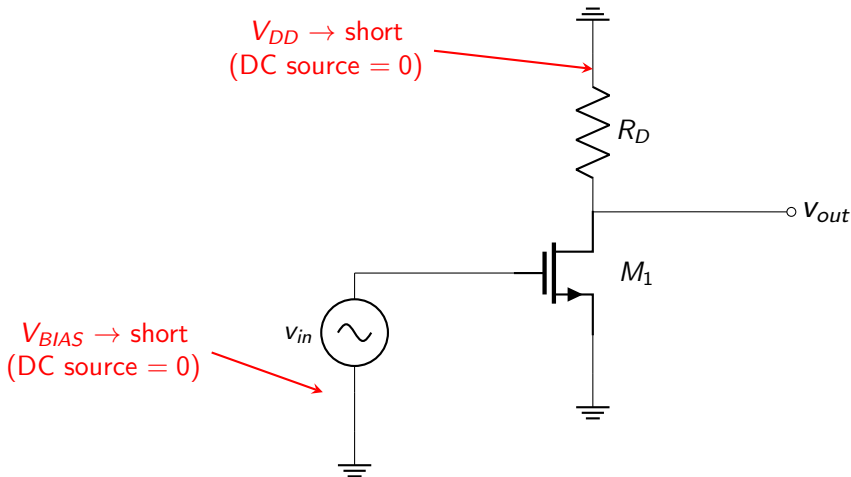
Comparison with BJT:

	BJT	MOSFET
g_m formula	$\frac{I_C}{V_T}$	$\frac{2I_{DS}}{V_{GS} - V_{TN}}$
Typical g_m	Higher (exponential)	Lower (square-law)

For the same current, BJT typically has higher g_m because $V_T \approx 26 \text{ mV} \ll V_{GS} - V_{TN}$.

(Sec. 7.2.4) Shorting DC Sources for Small-Signal Analysis

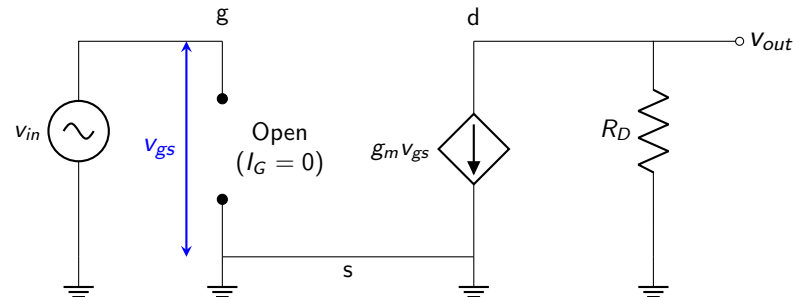
To analyze small-signal behavior, replace all DC voltage sources with short circuits:



Next step: replace the MOSFET with its small-signal model

(Sec. 7.2.4) Small-Signal Equivalent Circuit

Short all DC sources ($V_{BIAS} \rightarrow$ short, $V_{DD} \rightarrow$ short) and replace MOSFET with small-signal model:

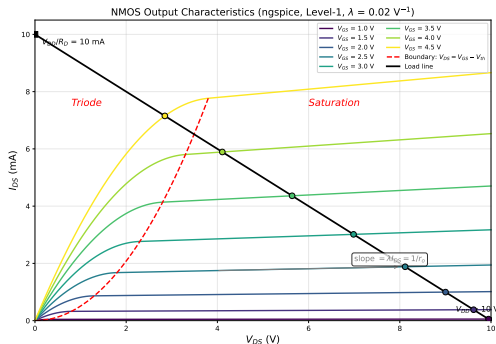


$$v_{gs} = v_{in}$$

$$v_{out} = -g_m v_{gs} \cdot R_D$$

$$A_v = \frac{v_{out}}{v_{in}} = -g_m R_D$$

(Sec. 7.2.4) Channel-Length Modulation $\Rightarrow$ Output Resistance r_o



With CLM, I_{DS} depends on V_{DS} :

$$I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2 (1 + \lambda V_{DS})$$

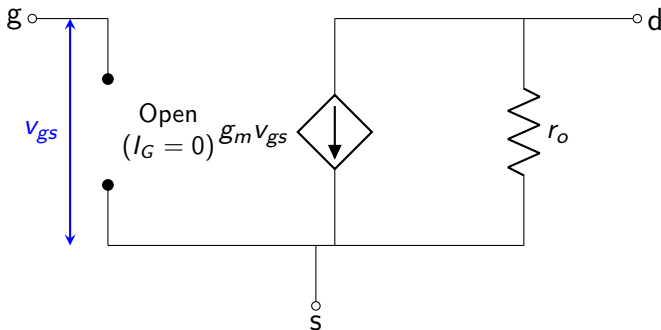
The saturation curves have a slight upward slope:

$$\left. \frac{\partial I_{DS}}{\partial V_{DS}} \right|_Q = \lambda I_{DS} \Rightarrow \boxed{r_o = \frac{1}{\lambda I_{DS}}}$$

Red dashed line: triode-saturation boundary ($V_{DS} = V_{GS} - V_{TN}$)

r_o acts as a **resistor** in parallel with the current source $g_m v_{gs}$.

(Sec. 7.2.4) Complete Small-Signal Model of the NMOS



$$g_m = \frac{2I_{DS}}{V_{GS} - V_{TN}} = K_n(V_{GS} - V_{TN})$$

$$r_o = \frac{1}{\lambda I_{DS}}$$

$$A_v = \frac{v_{out}}{v_{in}} = -g_m(R_D \parallel r_o) = -g_m \frac{R_D r_o}{R_D + r_o}$$

(Sec. 7.2) BJT vs MOSFET: Small-Signal Comparison

Parameter	BJT (npn)	NMOS MOSFET
Input impedance	$r_{\pi} = \beta/g_m$ (finite)	∞ (gate is insulated)
Transconductance	$g_m = I_C/V_T$	$g_m = 2I_{DS}/(V_{GS} - V_{TN})$
Output resistance	$r_o = V_A/I_C$	$r_o = 1/(\lambda I_{DS})$
Voltage gain	$A_v = -g_m(R_C \parallel r_o)$	$A_v = -g_m(R_D \parallel r_o)$
Input current	$i_b = v_{be}/r_{\pi}$	$i_{gs} = 0$

Typical Values of $\mu_n C_{ox}$ for Lecture Examples

The **process transconductance parameter** $k'_n \equiv \mu_n C_{ox}$ is set by fabrication (μ_n and t_{ox}), not by the designer.

Defensible classroom ranges for NMOS:

Regime	$\mu_n C_{ox}$
Conservative (older, thick-oxide process)	$\approx 70 \mu\text{A}/\text{V}^2$
Typical textbook ($0.25\text{--}0.18 \mu\text{m}$)	$100\text{--}200 \mu\text{A}/\text{V}^2$
Aggressive but still reasonable for hand analysis	$250\text{--}300 \mu\text{A}/\text{V}^2$

For EE461 we use $\mu_n C_{ox} = 200 \mu\text{A}/\text{V}^2$ — a clean mid-range value for hand analysis.

Supporting data: a measured $1.6 \mu\text{m}$ CMOS process (gate oxide $306 \text{ \AA}$) reports $K' = \mu_n C_{ox}/2 = 35.7 \mu\text{A}/\text{V}^2$, i.e. $\mu_n C_{ox} \approx 71 \mu\text{A}/\text{V}^2$. Modern short-channel processes push $\mu_n C_{ox}$ well above $200 \mu\text{A}/\text{V}^2$.

Notation Warning: k'_n vs K'

Different textbooks split the factor of $\frac{1}{2}$ differently — check which convention your source uses before quoting a number:

Convention A (Razavi, Sedra/Smith):

$$I_D = \frac{1}{2} \underbrace{\mu_n C_{ox}}_{k'_n} \frac{W}{L} V_{OV}^2$$

Report $k'_n = \mu_n C_{ox}$ directly (~ 100 – $300 \mu\text{A}/\text{V}^2$).

Convention B (older books, some datasheets):

$$I_D = K' \frac{W}{L} V_{OV}^2, \quad K' = \frac{\mu_n C_{ox}}{2}$$

Reported K' is **half** of k'_n (~ 50 – $150 \mu\text{A}/\text{V}^2$).

Mixing the two conventions gives a **factor-of-two error** in I_D . Always check which one is in play.

EE461 equation sheet convention: $K_n = \mu_n C_{ox} \cdot (W/L)$ and $I_{DS} = \frac{K_n}{2} (V_{GS} - V_{TN})^2$ — equivalent to Convention A with W/L pulled out.

Where $\mu_n C_{ox}$ Comes From

$$k'_n = \mu_n C_{ox} = \mu_n \cdot \frac{\varepsilon_{ox}}{t_{ox}}.$$

Two process-dependent pieces:

- μ_n — electron mobility in the channel (typ. 400–600 cm²/V · s in long-channel devices)
- $C_{ox} = \varepsilon_{ox}/t_{ox}$ — gate-oxide capacitance per unit area ($\varepsilon_{ox} = 3.9 \varepsilon_0 \approx 3.45 \times 10^{-11}$ F/m)

Example. For $t_{ox} = 10$ nm and $\mu_n = 500$ cm²/V · s:

$$C_{ox} = \frac{3.45 \times 10^{-11}}{10^{-8}} \approx 3.45 \text{ mF/m}^2$$

$$\mu_n C_{ox} \approx (0.05 \text{ m}^2/\text{V} \cdot \text{s})(3.45 \times 10^{-3} \text{ F/m}^2) \approx 170 \mu\text{A/V}^2.$$

Thinner oxide $\Rightarrow$ larger $C_{ox} \Rightarrow$ larger $\mu_n C_{ox}$. Newer processes have thinner oxides, hence higher k'_n .